

## Remarks

Prior to the referenced Office action, claims 17 and 19-29 were pending.

Claims 17 and 19 were rejected in the referenced Office action.

Claims 20-29 were allowed in the referenced Office action.

Claims 17 and 19 are currently amended.

Claims 17, 19, 20-29 are currently pending.

### Rejection of claim 17 as being anticipated by Bennett et al. (US 4,413,406)

The Examiner states in the referenced Office action:

"Bennett discloses, figure 1, a processing amorphous metal into packets by bonding with low melting point material comprising the steps of placing the bond metal sheet (12) adjacent to the base metal sheet (12) to form an adjacently base-bond sheet (26); and inductively heating the adjacently disposed base-bond sheet (26) by passing the base-bond sheet (26) through one or more induction coils (29) to form a bonded sheet."  
(Page 2, Section 2)

As noted by the Examiner the bonding process in Bennett is accomplished by the step of melting a low melting point material (24) that is discretely (e.g. Bennett Fig. 2A through Fig. 2D) deposited between opposing surfaces of identical (amorphous) metal sheets (12). There is no distinctly different bond metal sheet and base metal sheet that are directly bonded together as recited in claim 17. The Bennett process bonds identical metal sheets together by heating the discretely deposited low melting point material placed between the two identical sheets. The Bennett process does not sufficiently heat the identical metal sheets with the low melting point material deposited between them to a sufficient temperature to directly bond together the two identical metal sheets:

"The maximum melting temperature of 350° C. for these selected materials [referring to the low melting point material (24)] is less than a critical transformation temperature related to the amorphous metal [referring to the metal sheets (12)] having a typical value of 450 ° C. The critical typical temperature of 450 ° C. is the temperature which when reached or exceeded transforms the amorphous metal from its non-crystalline state to its crystalline state. If the amorphous metal is transformed to its crystalline state, its superior electrical qualities that provide for reduced electrical losses for the amorphous metal core 40 are substantially reduced.

The metallic deposit 24 provides an agent which when heated by heating means 29 to its desired temperature range of 50 ° to 350 ° C. and then cooled to its solid state bonds together the amorphous metal sheets

12. Various distribution patterns of the metallic deposit 24 applied to amorphous metal sheets 12 are shown on FIGS. 2A, 2B, 2C and 2D."  
(col. 5, line 60 to col. 6, line 9; underlining added for emphasis).

Applicants submit that Bennett, as interpreted by one of ordinary skill in the art, does not teach the claimed process as recited in claim 17, and therefore, claim 17 is not anticipated by Bennett.

Rejection of claim 19 as being unpatentable over Chapman (US 2,367,715) in view of Bennett (citation provided above)

Chapman bonds a base metal strip (45, 52, 54, 55, 62, 83, 104, 110 or 113) to a cladding metal strip (46, 53, 56 and 57, 61, 63 and 64, 85 or 96) by induction heating the cladding metal strip and base metal strip prior to bonding the two strips together. Further, Chapman surrounds exclusively either the cladding metal strip (FIG. 3, FIG. 4, FIG. 5, FIG. 6, FIG. 7, FIG. 9, FIG. 11 FIG. 12, FIG. 15 and FIG. 16), or the base metal strip (FIG. 8, FIG. 10, and FIG. 13) with an induction coil for induction heating of either strip.

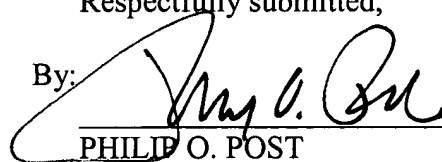
Bennett is discussed above. The Bennett process does not teach melting a bond metal sheet from the heat of an inductively heated base metal sheet to bond the bond metal sheet to the base metal sheet, and cutting the one or more bonded products from the formed bonded base-bond sheet as recited in claim 19.

Applicants submit that Chapman, in combination with Bennett, does not teach or suggest, the process recited in claim 19, and therefore, claim 19 is not obvious over Chapman in view of Bennett.

Applicants request allowance of all pending claims.

Respectfully submitted,

By:

 23 JUNE 2006

PHILIP O. POST

USPTO Reg. No. 28,456

Indel, Inc.

Post Office Box 157

Rancocas, New Jersey 08073

Telephone: (609) 267-9000, ext. 254

Facsimile: (609) 267-5705

CUSTOMER NO. 31855